

IGBT – Power, Co-PAK N-Channel, Field Stop VII (FS7), TO247-4L 1200 V, 1.7 V, 75 A

FGY4L75T120SWD

Description

Using the novel field stop 7th generation IGBT technology and the Gen7 Diode in TO247 4-lead package, FGY4L75T120SWD offers the optimum performance with low switching and conduction losses for high-efficiency operations in various applications like Solar Inverter, UPS and ESS.

Features

- Maximum Junction Temperature $T_J = 175$ °C
- Positive Temperature Coefficient for Easy Parallel Operation
- High Current Capability
- Smooth and Optimized Switching
- Low Switching Loss
- RoHS Compliant

Applications

- Solar Inverter
- UPS
- Energy Storage System

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

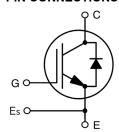
Param	Symbol	Value	Unit	
Collector-to-Emitter Volt	V _{CE}	1200	V	
Gate-to-Emitter Voltage		V _{GE}	±20	
Transient Gate-to-Emitte	er Voltage	1	±30	
Collector Current	T _C = 25°C (Note 1)	I _C	150	Α
	T _C = 100°C	1	75	
Power Dissipation	T _C = 25°C	P _D	555	W
	T _C = 100°C	1	278	
Pulsed Collector Current	T _C = 25°C, t _p = 10 μs (Note 2)	I _{CM}	300	Α
Diode Forward $T_C = 25^{\circ}C$ (Note 1)		Ι _Ε	150	
Current T _C = 100°C		1	75	
Pulsed Diode Forward Current	I _{FM}	300		
Operating Junction and S Range	T _J , T _{stg}	-55 to +175	°C	
Lead Temperature for So	T_L	265		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Value limited by bond wire
- 2. Repetitive rating: Pulse width limited by max. junction temperature.

BV _{CES}	V _{CE(SAT)_TYP}	lc
1200 V	1.7 V	75 A

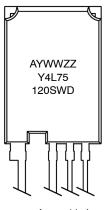
PIN CONNECTIONS





TO-247-4LD CASE 340BW

MARKING DIAGRAM



A = Assembly Location
YWW = Date code (Year & week)
ZZ = Assembly Lot
Y4L75120SWD = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
FGY4L75T120SWD	TO-247-4LD (Pb-Free)	30 Units / Tube

THERMAL CHARACTERISTICS

		Value			
Parameter	Symbol	Min	Тур	Max	Unit
Thermal Resistance, Junction-to-Case for IGBT	$R_{ heta JC}$	_	0.18	0.27	°C/W
Thermal Resistance, Junction-to-Case for Diode	$R_{\theta JCD}$	_	0.3	0.45	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	-	-	40	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS					-	
Collector-to-Emitter Breakdown Voltage	BV _{CES}	V _{GE} = 0 V, I _C = 1 mA	1200	_	-	V
Breakdown Voltage Temperature Coefficient	ΔBV_CES	$V_{GE} = 0 \text{ V, } I_{C} = 9.99 \text{ mA}$	-	1120	-	mV/°C
	ΔT_{J}					
Collector-to-Emitter Cut-Off Current	I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	-	-	40	μΑ
Gate-to-Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 20 \text{ V}, V_{CE} = 0 \text{ V}$	-	_	±400	nA
ON CHARACTERISTICS						
Gate-to-Emitter Threshold Voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 75 \text{ mA}$	5.6	6.5	7.4	V
Collector-to-Emitter Saturation Voltage	V _{CE(sat)}	V _{GE} = 15 V, I _C = 75 A, T _J = 25°C	-	1.7	2.0	
		V _{GE} = 15 V, I _C = 75 A, T _J = 175°C	-	2.4	-	
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{ies}	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	-	7190	-	pF
Output Capacitance	C _{oes}]	-	222	-	
Reverse Transfer Capacitance	C _{res}]	-	30.1	-	
Total Gate Charge	Qg	V _{CE} = 600 V, V _{GE} = 15 V, I _C = 75 A	-	225.6	-	nC
Gate-to-Emitter Charge	Q_{ge}	I _C = 75 A	-	66.4	-	
Gate-to-Collector Charge	Q_{gc}]	-	84.8	-	
SWITCHING CHARACTERISTIC, INDUCTIV	E LOAD					
Turn-on Delay Time	t _{d(on)}	$V_{CE} = 600 \text{ V}, V_{GE} = 15 \text{ V}$ $I_{C} = 37.5 \text{ A R}_{G} = 11.5 \Omega T_{J} = 25^{\circ}\text{C}$	-	62.8	-	ns
Rise Time	t _r	$I_{C} = 37.5 \text{ A H}_{G} = 11.5 \Omega I_{J} = 25^{\circ}\text{C}$	-	20.8	-	
Turn-off Delay Time	t _{d(off)}]	-	273.6	-	
Fall Time	t _f]	-	74	-	
Turn-on Switching Loss	E _{on}]	-	1.6	-	mJ
Turn-off Switching Loss	E _{off}]	-	1.2	-	1
Total Switching Loss	E _{ts}]	-	2.8	-	
Turn-on Delay Time	t _{d(on)}	V_{CE} = 600 V, V_{GE} = 15 V I_{C} = 75 A R_{G} = 11.5 Ω T_{J} = 25°C	-	65.6	-	ns
Rise Time	t _r	$I_C = 75 \text{ A H}_G = 11.5 \Omega \text{ T}_J = 25^{\circ}\text{C}$	-	28.8	-	
Turn-off Delay Time	t _{d(off)}	1	-	241.6	-	
Fall Time	t _f		-	62.4	-	
Turn-on Switching Loss	E _{on}		-	2.9	-	mJ
Turn-off Switching Loss	E _{off}		-	2.1	-	
Total Switching Loss	E _{ts}]	-	5.0	_	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted) (continued)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
SWITCHING CHARACTERISTIC, INDUC	CTIVE LOAD					
Turn-on Delay Time	t _{d(on)}	V _{CE} = 600 V, V _{GE} = 15 V	-	51.2	-	ns
Rise Time	t _r	I _C = 37.5 A R _G = 11.5 Ω T _J = 175°C	-	24.0	-	1
Turn-off Delay Time	t _{d(off)}		-	323.2	-	1
Fall Time	t _f		-	126.4	-	1
Turn-on Switching Loss	E _{on}		-	3.1	-	mJ
Turn-off Switching Loss	E _{off}		-	1.8	-	1
Total Switching Loss	E _{ts}		-	4.9	-	1
Turn-on Delay Time	t _{d(on)}	V _{CE} = 600 V, V _{GE} = 15 V	-	57.2	-	ns
Rise Time	t _r	$I_C = 75 \text{ A R}_G = 11.5 \Omega \text{ T}_J = 175^{\circ}\text{C}$	-	35.2	-	1
Turn-off Delay Time	t _{d(off)}		-	280	-	1
Fall Time	t _f		-	104	-	1
Turn-on Switching Loss	E _{on}		-	5.2	-	mJ
Turn-off Switching Loss	E _{off}		-	2.8	-]
Total Switching Loss	E _{ts}		-	8.1	-	1
DIODE CHARACTERISTICS	•					-
Forward Voltage	V _F	I _F = 75 A, T _J = 25°C	1.74	2.04	2.34	V
		I _F = 75 A, T _J = 175°C	-	2.2	-	
DIODE SWITCHING CHARACTERISTIC	S, INDUCTIVE LO	DAD				
Reverse Recovery Time	t _{rr}	V_R = 600 V, I _F = 37.5 A, dI _F /dt = 1000 A/ μ s, T _J = 25°C	-	145.3	-	ns
Reverse Recovery Charge	Q _{rr}		-	2.56	-	μС
Reverse Recovery Energy	E _{REC}		-	0.77	-	mJ
Peak Reverse Recovery Current	I _{RRM}]	-	35.2	=	Α
Reverse Recovery Time	t _{rr}	V _R = 600 V, I _F = 75 A,	-	208	=	ns
Reverse Recovery Charge	Q _{rr}	$dI_F/dt = 1000 \text{ A/}\mu\text{s}, T_J = 25^{\circ}\text{C}$	-	4.22	-	μC
Reverse Recovery Energy	E _{REC}		-	1.32	=	mJ
Peak Reverse Recovery Current	I _{RRM}]	-	40.6	=	Α
Reverse Recovery Time	t _{rr}	V_{R} = 600 V, I_{F} = 37.5 A, dI_{F}/dt = 1000 A/ μ s, T_{J} = 175°C	-	221.7	=	ns
Reverse Recovery Charge	Q _{rr}		-	5.54	=	μС
Reverse Recovery Energy	E _{REC}		-	1.85	-	mJ
Peak Reverse Recovery Current	I _{RRM}	1	-	48.7	-	Α
Reverse Recovery Time	t _{rr}	V _R = 600 V, I _F = 75 A,	-	307.1	-	ns
Reverse Recovery Charge	Q _{rr}	dI _F /dt = 1000 A/μs, T _J = 175°C	-	9.15	-	μC
Reverse Recovery Energy	E _{REC}		-	2.95	-	mJ
Peak Reverse Recovery Current	I _{RRM}	1	-	59.5	-	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

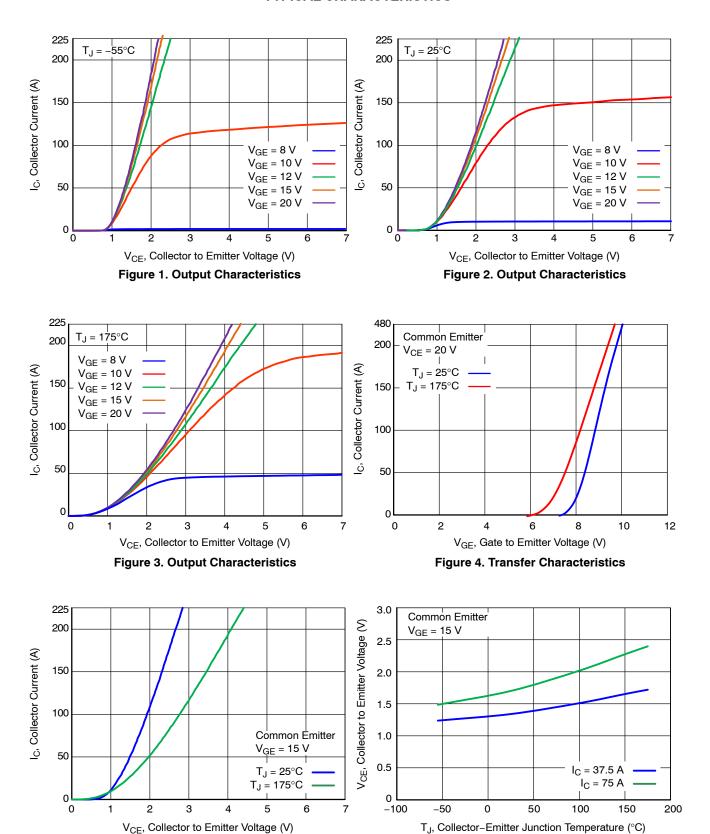


Figure 5. Saturation Characteristics

Figure 6. Saturation Voltage vs. Junction Temperature

TYPICAL CHARACTERISTICS

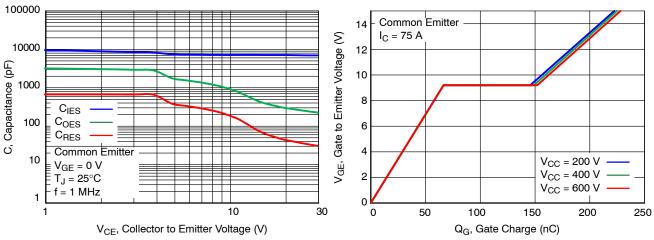


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics

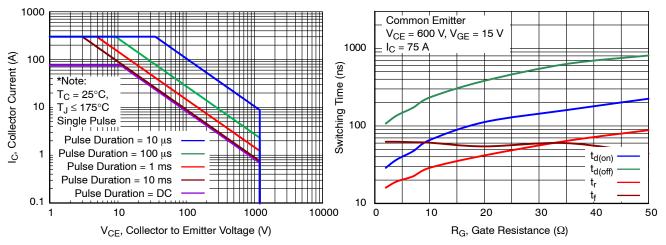


Figure 9. SOA Characteristics

Figure 10. Switching Time vs. Gate Resistance $(T_J = 25^{\circ}C)$

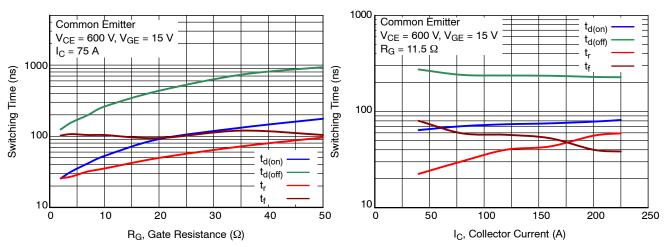


Figure 11. Switching Time vs. Gate Resistance $(T_J = 175^{\circ}C)$

Figure 12. Switching Time vs. Collector Current $(T_J = 25^{\circ}C)$

TYPICAL CHARACTERISTICS

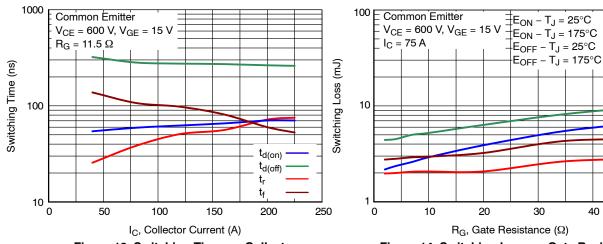


Figure 13. Switching Time vs. Collector Current (T_J = 175°C)

Figure 14. Switching Loss vs Gate Resistance

40

50

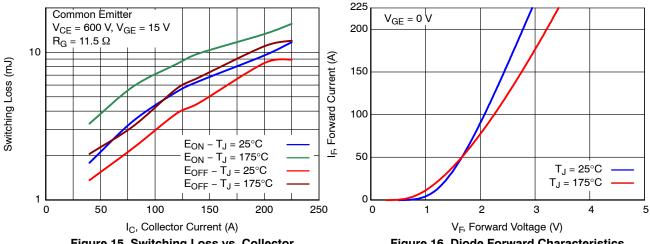


Figure 15. Switching Loss vs. Collector Current

Figure 16. Diode Forward Characteristics

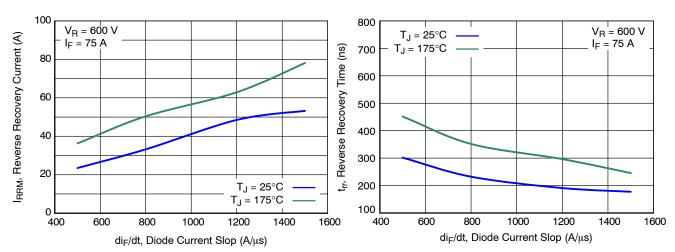


Figure 17. Diode Reverse Recovery Current

Figure 18. Diode Reverse Recovery Time

TYPICAL CHARACTERISTICS

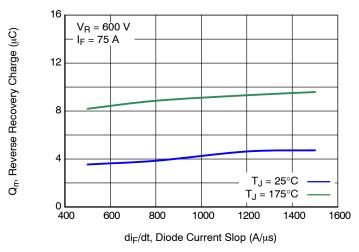


Figure 19. Diode Stored Charge

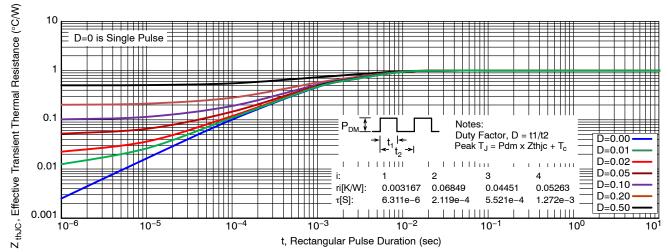


Figure 20. Max Transient Thermal Impedance of IGBT

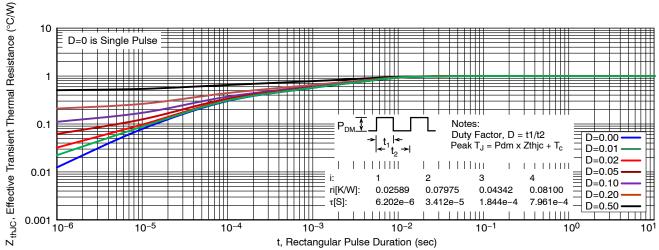
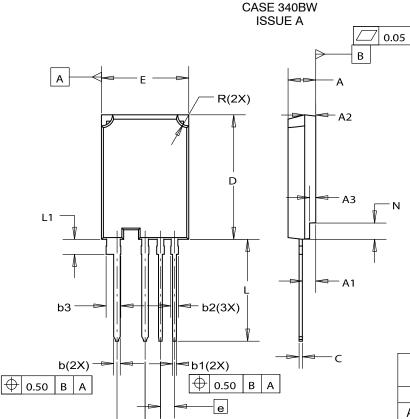


Figure 21. Max Transient Thermal Impedance of Diode

PACKAGE DIMENSIONS

TO-247-PLUS-4L 15.80x22.54x5.00, 2.54P



NOTES:

e2

A. NO INDUSTRY STANDARS APPLIES TO THIS PACKAGE. B. ALL DIMENSIONS ARE IN MILLIMETERS.

e1

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

D. DRAWING CONFORMS TO ASME Y14.5-2009.

_		_				
	MILLIMETERS					
	MIN	NOM	MAX			
Α	4.80	5.00	5.20			
Α1	2.21	2.41	2.61			
A2	1.80	2.00	2.20			
А3	1.00	1.10	1.20			
b	1.07	1.20	1.33			
b1	0.57	0.70	0.83			
b2	1.20	1.40	1.60			
b3	2.47	2.67	2.87			
С	0.50	0.60	0.70			
D	22.34	22.54	22.74			
D1	16.00	16.20	16.40			
D2	0.96	1.16	1.36			
D3	1.52	1.72	1.92			
е	2	2.54BSC				
e1	2	2.79BSC)			
e2	5.08BSC					
Ε	15.60	15.80	16.00			
E1	13.10	13.30	13.50			
L	18.12	18.42	18.72			
L1	2.52	2.72	2.92			
R	1.90	2.00	2.10			
Ν	2.75	2.95	3.15			

- E1 -

- D2

D₁

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